

Ceramic Resonator

1. SCOPE

This specification shall cover the characteristics of the ceramic resonator with the type ZTTCC8.00MG.

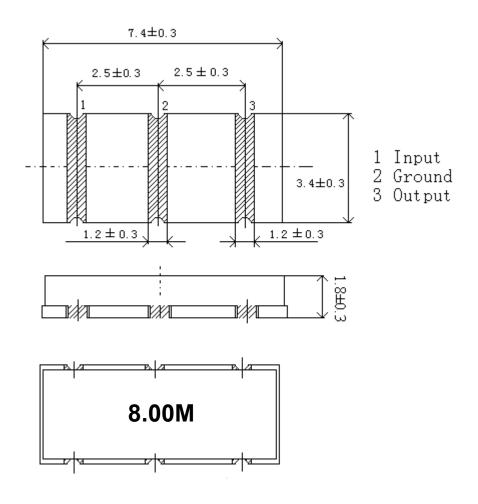
2. PART NO.:

PART NUMBER	CUSTOMER PART NO	SPECIFICATION NO
ZTTCC8.00MG		

3. OUTLINE DRAWING AND DIMENSIONS:

Appearance: No visible damage and dirt.

Dimensions:



UINT: mm





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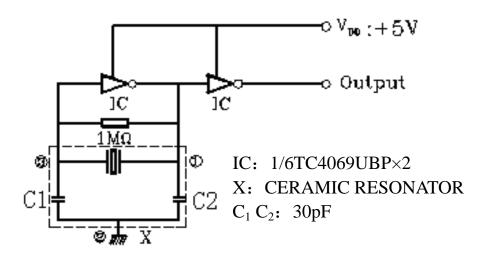
4. ELECTRICAL SPECIFICATIONS:

No	Item	Requirements	
4.1	Oscillation Frequency Fosc (MHz)	8.00	
	Frequency Accuracy (%)	±0.5	
4.2	Resonant Impedance Ro (Ω)max	30	
4.3	Temperature Coefficient of	± 0.3 (Oscillation Frequency	
	Oscillation Frequency (%) max	drift -20°C to $+80^{\circ}\text{C}$)	
4.4	Withstanding Voltage	50 VDC, 1 min	
4.5	Rating Voltage U _R (V)		
	(1) D.C. Voltage	6 VDC.	
	(2) A.C. Voltage	15 Vp-p.	
4.6	Insulation Resistance Ri, $(M \Omega)$ min	100 (100V, 1min)	
4.7	Operating Temperature (°C)	-40~+85	
4.8	Storage Temperature $(^{\circ}C)$	-55∼+85	
4.9	Aging Rate (%) max	± 0.3 (For 10 years)	

5. MEASUREMENT:

Measurement Conditions: Parts shall be measured under a condition (Temp.: 20 ± 15 °C ,Humidity : $65\pm20\%$ R.H.) unless the standard condition(Temp.: 25 ± 3 °C ,Humidity : $65\pm5\%$ R.H.) is regulated to measure.

Test Circuit:





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6. PHYSICAL AND ENVIRONMENTAL CHARACTERISTICS

No	Item	Condition of Test	Performance	
			Requirements	
6.1	Humidity	Keep the resonator at 40±2℃ and 90	It shall fulfill	
		for 96±4 hours. Then Release the reso	onator into	the
		the room Condition for 1 hour pri	ior to the	specifications
		Measurement.		in Table 1.
6.2	Vibration	Subject the resonator to vibration for	or 2 hours	It shall fulfill
		each in x, y and z axis With the am	plitude of	the
		1.5mm, the frequency shall be varied	uniformly	specifications
		between the limits of 10 Hz—55Hz.		in Table 1.
6.3	Mechanical	Drop the resonator randomly onto	a wooden	It shall fulfill
	Shock	floor from the height of 100cm 3 time	es.	the
				specifications
				in Table 1.
6.4	Soldering	Passed through the re-flow oven	under the	It shall fulfill
	Test	following condition and left	at room	the
		temperature for 1 hour before measure	ement.	specifications
		Temperature at the surface of the	Time	in Table 1.
		substrate		
		Preheat 150±5°C	60±10	
			sec	
		Peak 240±5°C	10±3 sec	
6.5	Solder	Dipped in 230±5°C solder bath for	3±0.5 sec	The terminals
	Ability	seconds with rosin flux (25wt%)	ethanol	shall be at
		solution.)		least 95%
				covered by
				solder.
6.6	High	Subject the resonator to 80±5°C for		It shall fulfill
	Temperature	then release the resonator into	the	
	Exposure	conditions for 1 hour prior to the mea	specifications	
			in Table 1.	
6.7	Low	Subject the resonator to -20 ± 5 °C for	It shall fulfill	
	Temperature	then release the resonator into	the	
	Exposure	conditions for 1 hour prior to the mea	surement.	specifications
				in Table 1.



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6. PHYSICAL AND ENVIRONMENAL CHARACTERISICS

(Continued from the preceding page)

No	Item	Condition of Test	Performance
			Requirements
6.8	Temperature	Subject the resonator to -40°C for 30	It shall fulfill the
	Cycling	min. followed by a high temperature of	specifications in
		85°C for 30 min.	Table 1.
		Cycling shall be repeated 5 times with a	
		transfer time of 15 sec. At the room	
		temperature for 1 hour prior to the	
		measurement.	
6.9	Board	Mount a glass-epoxy board	Mechanical damage
	Bending	(Width=40mm,thickness=1.6mm),then bend it	such as breaks shall
		to 1mm displacement and keep it for 5 seconds.	not occur.
		(See the following figure)	
		PRESS	
		20	
		PRESS HEAD	
		D.U.T. 04	
		D.U.T. 2.0 + 0.1	
		45±2 45±2	
		<u>∕ø5 SUPPORT</u> BAR	

TABLE 1

Item	Specification	
Oscillation Frequency Change △Fosc/Fosc (%) max	±0.3	
Resonant Impedance Change $\triangle Ro(\Omega)$ max	±10	

Note: The limits in the above table are referenced to the initial measurements.



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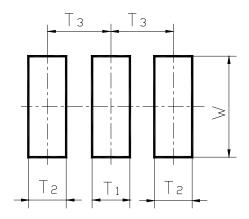
7. REVIEW OF SPECIFICATIONS

When something gets doubtful with this specifications, we shall jointly work to get an agreement.

8. RECOMMENDED LAND PATTERN AND REFLOW SOLDERING

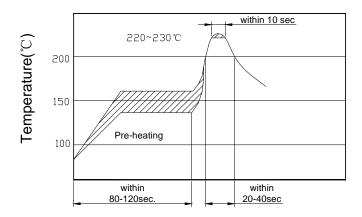
STANDARD CONDITIONS

8.1Recommended land pattern



DIMENSIONS (mm)					
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1.5±0.3 1.7±0.3		2.5±0.3	4.0±0.3		

8.2Recommended reflow soldering standard conditions



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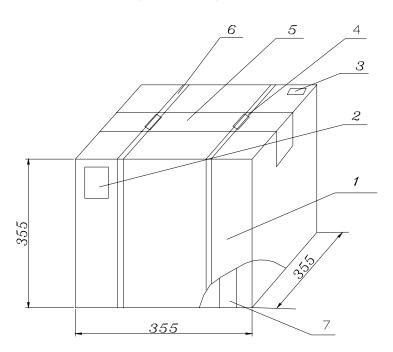
9. PACKAGE

To protect the products in storage and transportation, it is necessary to pack them (outer and inner package). On paper pack, the following requirements are requested.

Dimensions and Mark

At the end of package, the warning (moisture proof, upward put) should be stick to it.

Dimensions and Mark (see below)



NO.	Name	Quantity	Notes
1	Package	1	
2	Certificate of approval	1	
3	Label	1	
4	Tying	2	
5	Adhesive tape	1.2m	
6	Belt	2.9m	
7	Inner Box	10	

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Section of package

Package is made of corrugated paper with thickness of 0.8cm.Package has 10 inner boxes, each box has 1 reel(each reel for plastic bag)

Quantity of package

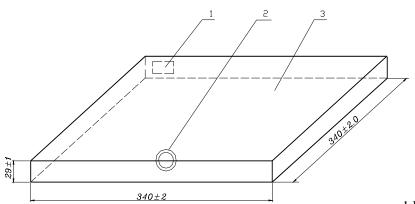
Per plastic reel 4000 pieces of piezoelectric ceramic part

Per inner box 1 reel

Per package 10 inner boxes (40000 pieces of piezoelectric

ceramic part)

Inner Packing Dimensions



1.UNIT: mm

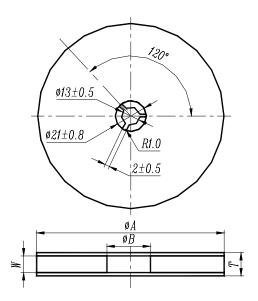
1	Label	
2	QC Label	
3	Inner Box	

Pars shall be packaged in box with hold down tape upside. Part No., quantity and lot No.



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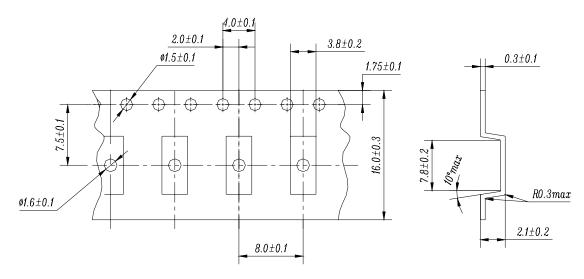
8.5Reel



Dimensions Unit: mm

φА	φВ	W	T	Pieces per reel	Carrier tape size
330 ± 3	80min	16.4min	22.4max	4000typ.	16

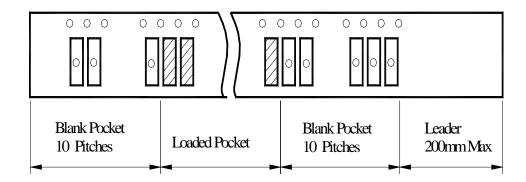
8.6Taping Dimensions





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8.7Packing Method Sketch Map



8.8Test Condition Of Peeling Strength

